

2N6520

High Voltage Transistor

- Collector-Emitter Voltage: V_{CEO}= -350V
 Collector Dissipation: P_C (max)=625mW
 Complement to 2N6517



1. Emitter 2. Base 3. Collector

PNP Epitaxial Silicon Transistor

Absolute Maximum Ratings T_a =25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{CBO}	Collector-Base Voltage	-350	V
V _{CEO}	Collector-Emitter Voltage	-350	V
V _{EBO}	Emitter-Base Voltage	-5	V
I _C	Collector Current	-500	mA
I _B	Base Current	-250	mA
P _C	Collector Power Dissipation	0.625	W
	Derate above 25	5	mW/°C
T _J	Junction Temperature	50	°C
T _{STG}	Storage Temperature	-55 ~ 150	°C

Electrical Characteristics T_a =25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
BV _{CBO}	Collector-Base Breakdown Voltage	I _C = -100μA, I _E =0	-350		V
BV _{CEO}	* Collector-Emitter Breakdown Voltage	I _C = -1mA, I _B =0	-350		V
BV _{EBO}	Emitter-Base Breakdown Voltage	I _E = -10μA, I _C =0	-5		V
I _{CBO}	Collector Cut-off Current	V _{CB} = -250V, I _E =0		-50	nA
I _{EBO}	Emitter Cut-off Current	V _{EB} = -4V, I _C =0		-50	nA
h _{FE}	* DC Current Gain	V_{CE} = -10V, I_{C} = -1mA V_{CE} = -10V, I_{C} = -10mA V_{CE} = -10V, I_{C} = -30mA V_{CE} = -10V, I_{C} = -50mA V_{CE} = -10V, I_{C} = -100mA	20 30 30 20 15	200 200	
V _{CE} (sat)	Collector-Emitter Saturation Voltage	I _C = -10mA, I _B = -1mA I _C = -20mA, I _B = -2mA I _C = -30mA, I _B = -3mA I _C = -50mA, I _B = -5mA		-0.30 -0.35 -0.50 -1	V V V
V _{BE} (sat)	Base-Emitter Saturation Voltage	I _C = -10mA, I _B = -1mA I _C = -20mA, I _B = -2mA I _C = -30mA, I _B = -3mA		-0.75 -0.85 -0.90	V V V
V _{BE} (on)	Base-Emitter On Voltage	V _{CE} = -10V, I _C = -100mA		-2	V
f _T	* Current Gain Bandwidth Product	V _{CE} = -20V, I _C = -10mA, f=20MHz	40	200	MHz
C _{ob}	Output Capacitance	V _{CB} = -20V, I _E =0, f=1MHz		6	pF
C _{EB}	Emitter-Base Capacitance	V _{EB} = -0.5V, I _C =0, f=1MHz		100	pF
t _{ON}	Turn On Time	V_{BE} (off)= -2V, V_{CC} = -100V I_{C} = -50mA, I_{B1} = -10mA		200	ns
t _{OFF}	Turn Off Time	V_{CC} = -100V, I_{C} = -50mA I_{B1} = I_{B2} = -10mA		3.5	ns

^{*} Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

Typical Characteristics

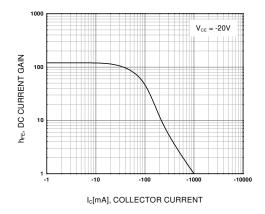


Figure 1. DC current Gain

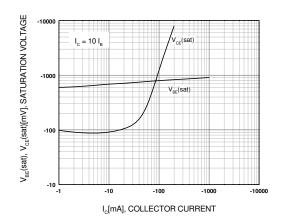


Figure 2. Base-Emitter Saturation Voltage Collector-Emitter Saturation Voltage

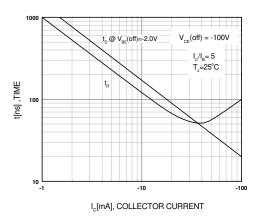


Figure 3. Turn-On Time

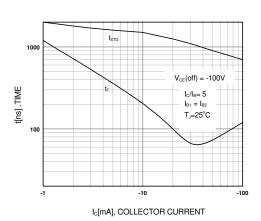


Figure 4. Turn-Off Time

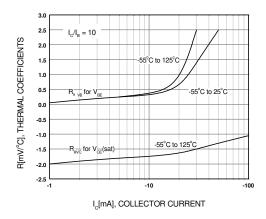


Figure 5. Temperature Coefficients

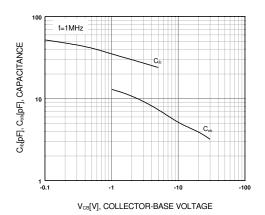


Figure 6. Capacitance

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Typical Characteristics (Continued)

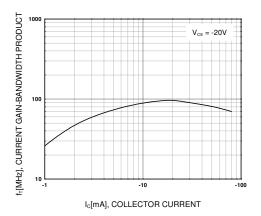
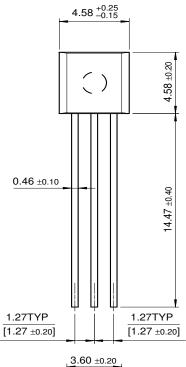
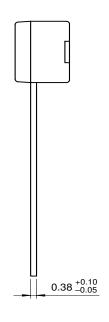


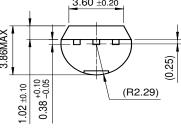
Figure 7. Current Gain Bandwidth Product

Package Dimensions

TO-92







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CROSSVOLT™	FRFET™	MicroPak™	QFET™	SuperSOT™-8
DOME™	GlobalOptoisolator™	MICROWIRE™	QS™	SyncFET™
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Programmable Active Droop™		OPTOPLANAR™	SMART START™	

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Rev. I1

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